

# PMEG6030ELPX-JSM Surface Mount Schottky Barrier Rectifier

#### **Features**

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- · Low power loss, high efficiency
- · High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications



#### **MECHANICAL DATA**

Case: SOD128

• Terminals: Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 27mg / 0.00095oz

#### **PINNING**

PIN	DESCRIPTION				
1	Cathode				
2	Anode				

#### Absolute Maximum Ratings and Electrical characteristics

Ratings at 25  $^{\circ}$ C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20  $^{\circ}$ C

Parameter	Symbols	PMEG6030ELPX			
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	60	V		
Maximum RMS voltage	V <sub>RMS</sub>	42	٧		
Maximum DC Blocking Voltage	V <sub>DC</sub>	60	V		
Maximum Average Forward Rectified Current	I <sub>F(AV)</sub>	3.0	Α		
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I <sub>FSM</sub>	80	А		
Max Instantaneous Forward Voltage at 3 A	V <sub>F</sub>	0.70	٧		
Maximum DC Reverse Current $T_a = 25^{\circ}$ C at Rated DC Reverse Voltage $T_a = 100^{\circ}$ C	I <sub>R</sub>	0.5 5	mA		
Typical Junction Capacitance <sup>(1)</sup>	Cj	250	pF		
Typical Thermal Resistance (2)	R <sub>θJA</sub>	70 18	°C/W		
Operating Junction Temperature Range	Tj	-55 ~ +150	°C		
Storage Temperature Range	T <sub>stg</sub>	-55 ~ +150	°C		

<sup>(1)</sup> Measured at 1 MHz and applied reverse voltage of 4 V D.C

<sup>(</sup> 2 ) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.



Fig.1 Forward Current Derating Curve

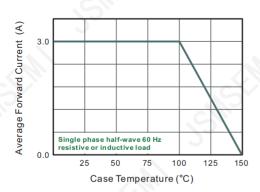


Fig.2 Typical Reverse Characteristics

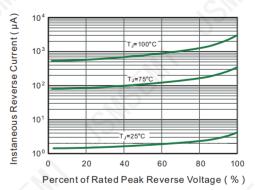


Fig.3 Typical Forward Characteristic

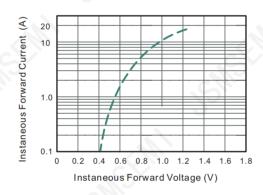


Fig.4 Typical Junction Capacitance

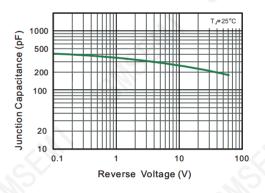


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

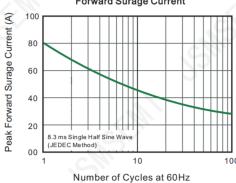
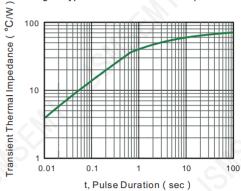


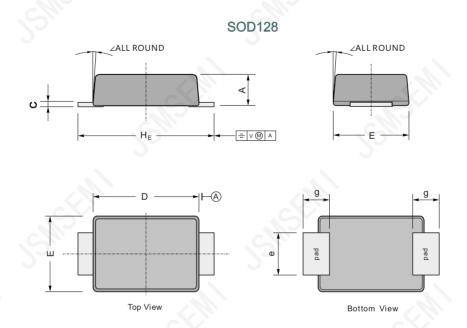
Fig.5- Typical Transient Thermal Impedance





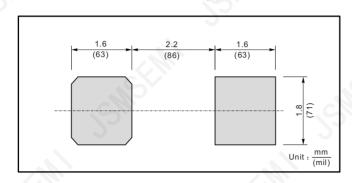
# PACKAGE OUTLINE

## Plastic surface mounted package; 2 leads



UNIT		Α	С	D	Е	е	g	HE	<b>∠</b>
mm	max	1.2	0.20	3.7	2.7	1.6	1.2	4.9	
	min	0.9	0.12	3.3	2.4	1.3	0.8	4.4	7°
mil	max	47	7.9	146	106	63	47	193	/
	min	35	4.7	130	94	51	31	173	

### The recommended mounting pad size





## **Revision History**

Rev.	Change	Date
V1.0	Initial version	2/23/2024
-11		

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